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(54) Title: WAFER POLISHING SYSTEM AND WAFER PROCESSING METHOD

(54) 发明名称: 一种晶圆抛光系统及晶圆处理方法

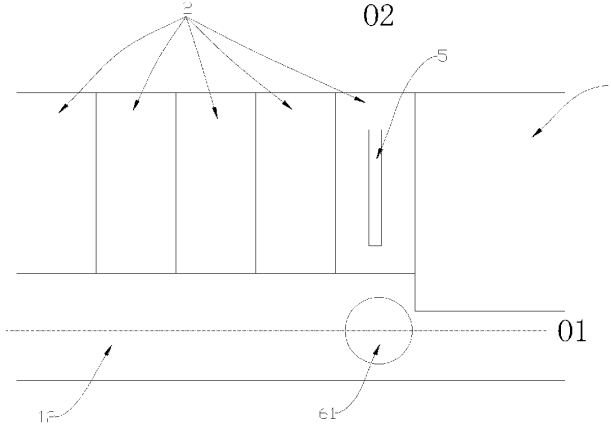


图 1

(57) Abstract: Disclosed in the present invention is a wafer polishing system, comprising a wafer polishing unit, a wafer cleaning unit which is arranged adjacent to the wafer polishing unit, a wafer transport channel, and a wafer transfer mechanism, at least part thereof being located in the wafer cleaning unit. A docking station is formed on the wafer transport channel, and at least part of the wafer transfer mechanism can move to the docking station, so as to transport wafers between the wafer polishing unit and the wafer cleaning unit. Further disclosed in the present invention is a wafer processing method of the wafer polishing system. In the present invention, part of the wafer transfer mechanism is located in the wafer cleaning unit, and said part can move to the docking station so as to achieve direct interaction between the wafer polishing unit and the wafer cleaning unit without any intermediate interaction link. Moreover, shortening the transfer path of wafers also reduces devices needed for wafer transferring, thereby minimizing the damage to wafers and achieving high efficiency of wafer transferring.

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本国际公布:
— 包括国际检索报告(条约第21条(3))。

(57) 摘要: 本发明公开了一种晶圆抛光系统，包括：晶圆抛光单元；晶圆清洗单元，与晶圆抛光单元相邻设置；晶圆传输通道；还包括晶圆转移机构，至少部分位于晶圆清洗单元；晶圆传输通道上形成有对接工位，晶圆转移机构的至少部分可活动至对接工位，以实现晶圆在晶圆抛光单元和晶圆清洗单元之间的传输。本发明还公开了一种晶圆抛光系统的晶圆处理方法。本发明晶圆转移机构的部分位于晶圆清洗单元内，其部分可以活动至对接工位，实现了晶圆抛光单元和晶圆清洗单元之间的直接交互，省去了中间的交互环节，晶圆的传递路径缩短，也减少了晶圆传递需要借助的装置，对晶圆的损伤降至最低，晶圆传输效率高。